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**Yoshiki Nakata
Xianfan Xu
Stephan Roth
Beat Neuenschwander**
Editors

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The CID Number appears on each page of the manuscript. The complete citation is used on the first page, and an abbreviated version on subsequent pages. Numbers in the index correspond to the last two digits of the six-digit CID Number.

Contents

ix *Conference Committee*

LASER-INDUCED MODIFICATION AND PATTERNING OF SURFACES I: JOINT SESSION WITH CONFERENCES 8967 AND 8969

- 8967 04 **Real-time adaptive optimization of laser induced nano ripples by laser pulse shaping** [8967-3]
P. Srisungsitthisunti, King Mongkut's Univ. of Technology North Bangkok (Thailand);
M. Zamfirescu, L. P. Neagu, National Institute for Lasers, Plasma and Radiation Physics (Romania); N. Faure, R. Stoian, Lab. Hubert Curien, CNRS, Univ. de Lyon, Univ. Jean Monnet (France)

LASER-INDUCED MODIFICATION AND PATTERNING OF SURFACES II: JOINT SESSION WITH CONFERENCES 8967 AND 8969

- 8967 05 **Laser-induced patterns on metals and polymers for biomimetic surface engineering (Invited Paper)** [8967-4]
A.-M. Kietzig, J. Lehr, L. Matus, F. Liang, McGill Univ. (Canada)

NANOMATERIAL PHOTONICS AND PLASMONICS I: JOINT SESSION WITH CONFERENCES 8967 AND 8969

- 8967 07 **Optothermal response of plasmonic nanofocusing lens under picosecond laser irradiation (Invited Paper)** [8967-6]
Z. Du, C. Chen, L. Traverso, X. Xu, L. Pan, Purdue Univ. (United States); I.-H. Chao, A. S. Lavine, Univ. of California, Los Angeles (United States)

ULTRAFAST LASER-INDUCED MODIFICATIONS OF TRANSPARENT MATERIALS: JOINT SESSION WITH CONFERENCES 8967 AND 8972

- 8967 08 **Femtosecond laser 3D nanofabrication in glass: enabling direct write of integrated micro/nanofluidic chips (Invited Paper)** [8967-7]
Y. Cheng, Y. Liao, Shanghai Institute of Optics and Fine Mechanics (China); K. Sugioka, RIKEN-SIOM Joint Research Unit (Japan)
- 8967 09 **Flexible metal patterning in glass microfluidic structures using femtosecond laser direct-write ablation followed by electroless plating** [8967-8]
J. Xu, K. Midorikawa, K. Sugioka, RIKEN (Japan)

- 8967 0A **Nanosecond laser-induced back side wet etching of fused silica with a copper-based absorber liquid** [8967-9]
P. Lorenz, Leibniz-Institut für Oberflächenmodifizierung e.V. (Germany); S. Zehnder, Bern Univ. of Applied Sciences (Switzerland); M. Ehrhardt, F. Frost, K. Zimmer, Leibniz-Institut für Oberflächenmodifizierung e.V. (Germany); P. Schwaller, Bern Univ. of Applied Sciences (Switzerland)
- 8967 0B **Picosecond-laser bulk modification, luminescence, and Raman lasing in single-crystal diamond** [8967-10]
B. Neuenschwander, B. Jaeggi, V. Romano, Bern Univ. of Applied Sciences (Switzerland); S. M. Pimenov, A. M. Prokhorov General Physics Institute (Russian Federation)
- 8967 0C **Dynamics of interference of femtosecond laser-induced stress waves and crack formation inside a LiF single crystal** [8967-11]
M. Sakakura, N. Fukuda, Y. Shimotsuma, K. Miura, Kyoto Univ. (Japan)

ADAPTIVE OPTICS AND BEAM SHAPING: JOINT SESSION WITH CONFERENCES 8967 AND 8972

- 8967 0F **Femtosecond laser processing and spatial light modulator (Invited Paper)** [8967-14]
K. Paivasaari, M. Silvennoinen, Univ. of Eastern Finland (Finland); J. Kaakkunen, VTT Technical Research Ctr. of Finland (Finland); P. Vahimaa, Univ. of Eastern Finland (Finland)
- 8967 0G **Focal length stabilization of a tunable lens integrated focus shifting unit** [8967-15]
G. Eberle, B. Boesser, ETH Zürich (Switzerland); K. Wegener, ETH Zürich (Switzerland) and Inspire AG (Switzerland)

ULTRASHORT PULSE MICROMACHINING: JOINT SESSION WITH CONFERENCES 8967 AND 8972

- 8967 0H **Influence of laser parameters on quality of microholes and process efficiency** [8967-16]
A. Feuer, C. Kunz, Univ. Stuttgart (Germany); M. Kraus, Robert Bosch GmbH (Germany); V. Onuseit, R. Weber, T. Graf, Univ. Stuttgart (Germany); D. Ingildeev, F. Hermanutz, Institut für Textilchemie und Chemiefasern Denkendorf (Germany)

MATERIALS FOR ENERGY CONSERVATION

- 8967 0J **Laser cutting of carbon fiber reinforced thermo-plastics (CFRTP) by single-mode fiber laser irradiation** [8967-18]
H. Niino, Y. Kawaguchi, T. Sato, A. Narazaki, Advanced Laser and Process Technology Research Association (Japan) and National Institute of Advanced Industrial Science and Technology (Japan); R. Kurosaki, Advanced Laser and Process Technology Research Association (Japan); M. Muramatsu, Y. Harada, Advanced Laser and Process Technology Research Association (Japan) and National Institute of Advanced Industrial Science and Technology (Japan); K. Anzai, M. Aoyama, Advanced Laser and Process Technology Research Association (Japan) and Miyachi Corp. (Japan); M. Matsushita, K. Furukawa,

Advanced Laser and Process Technology Research Association (Japan) and Shin Nippon Koki Co. Ltd. (Japan); M. Nishino, Advanced Laser and Process Technology Research Association (Japan) and Mitsubishi Chemical Corp. (Japan); A. Fujisaki, T. Miyato, T. Kayahara, Advanced Laser and Process Technology Research Association (Japan) and Furukawa Electric Co., Ltd. (Japan)

- 8967 OK **Laser trepanning of CFRP with a scanner head for IR and UV lasers** [8967-19]
K. Anzai, M. Aoyama, Advanced Laser and Process Technology Research Association (Japan) and Miyachi Corp. (Japan); A. Fujisaki, T. Miyato, T. Kayahara, Advanced Laser and Process Technology Research Association (Japan) and Furukawa Electric Co., Ltd. (Japan); Y. Harada, H. Niino, Advanced Laser and Process Technology Research Association (Japan) and National Institute of Advanced Industrial Science and Technology (Japan)
- 8967 OL **Ablation dynamics and shock wave expansion during laser processing of CFRP with ultrashort laser pulses** [8967-20]
M. Wiedenmann, C. Haist, C. Freitag, V. Onuseit, R. Weber, T. Graf, Univ. Stuttgart (Germany)
- 8967 OM **Analysis of laser ablation dynamics of CFRP in order to reduce heat affected zone** [8967-21]
Y. Sato, M. Tsukamoto, Osaka Univ. (Japan); T. Nariyama, Kinki Univ. (Japan); K. Nakai, Osaka Univ. (Japan); F. Matsuoka, Kinki Univ. (Japan); K. Takahashi, S. Masuno, Osaka Univ. (Japan); T. Ohkubo, Tokyo Institute of Technology (Japan); H. Nakano, Kinki Univ. (Japan)

ENHANCED PROCESSING BY MULTI-PULSE

- 8967 ON **Application of a laser heterodyne technique to characterize surface acoustic waves generated via a pulsed laser excitation** [8967-22]
A. J. Manzo, H. Helvajian, The Aerospace Corp. (United States)
- 8967 OO **Maximizing laser ablation efficiency of silicon through optimization of the temporal pulse shape** [8967-23]
A. Cournoyer, D. Gay, INO (Canada); P. Turbis, Univ. de Montréal (Canada); E. Lorin, Univ. de Montréal (Canada) and Carleton Univ. (Canada); M. Briand, Y. Taillon, INO (Canada)
- 8967 OP **Laser thin film ablation with multiple beams and tailored beam profiles** [8967-24]
S. Rung, Univ. of Applied Sciences Aschaffenburg (Germany); C. Bischoff, E. Jäger, U. Umhofer, TOPAG Lasertechnik GmbH (Germany); R. Hellmann, Univ. of Applied Sciences Aschaffenburg (Germany)
- 8967 OQ **High-throughput and high-precision laser micromachining with ps-pulses in synchronized mode with a fast polygon line scanner** [8967-25]
B. Jaeggi, B. Neuenschwander, M. Zimmermann, Bern Univ. of Applied Sciences (Switzerland); L. Penning, R. deLoor, Next Scan Technology B.V. (Netherlands); K. Weingarten, A. Oehler, Time-Bandwidth Products AG (Switzerland)

ANNEALING AND FORMING OF MICROSTRUCTURES

- 8967 OS **Precision laser annealing of silicon devices for enhanced electro-optic performance** [8967-27]
D. A. Bender, C. T. DeRose, A. Starbuck, J. C. Verley, M. W. Jenkins, Sandia National Labs. (United States)
- 8967 OT **Laser annealing and simulation of amorphous silicon thin films for solar cell applications** [8967-28]
I. Theodorakos, Y. S. Raptis, National Technical Univ. of Athens (Greece); V. Vamvakas, HelioSphera SA (Greece); D. Tsoukalas, I. Zergioti, National Technical Univ. of Athens (Greece)
- 8967 OU **Novel industrial laser etching technics for sensors miniaturization applied to biomedical: a comparison of simulation and experimental approach** [8967-29]
J. Zelgowski, Icube (France) and IREPA LASER (France) and Lab. Hubert Curien (France); F. Mermet, IREPA LASER (France); F. Antoni, Icube (France); C. Mauclair, Lab. Hubert Curien (France) and GIE Manutech-USD (France); E. Fogarassy, Icube (France); E. Mottay, Amplitude Systèmes (France)
- 8967 OV **Surface structuring of zirconium-based bulk metallic glasses using ultrashort laser pulses** [8967-30]
C. Dold, Inspire AG (Switzerland); M. Kachel, D. Wortmann, RWTH Aachen (Germany); V. Wessels, ETH Zürich (Switzerland); A. Dohrn, Fraunhofer-Institut für Lasertechnik (Germany); A. Bruinink, EMPA (Switzerland); F. Pude, Inspire AG (Switzerland); J. F. Loeffler, ETH Zürich (Switzerland); R. Poprawe, RWTH Aachen (Germany) and Fraunhofer-Institut für Lasertechnik (Germany); K. Wegener, Inspire AG (Switzerland) and ETH Zürich (Switzerland)

APPLICATIONS AND DIAGNOSTICS OF LASER TRANSFER TECHNIQUES: JOINT SESSION WITH CONFERENCES 8967 AND 8970

- 8967 OX **High-resolution imaging of ejection dynamics in laser-induced forward transfer** [8967-32]
R. Pohl, C. W. Visser, G. R. B. E. Römer, C. Sun, A. J. Huis in 't Veld, D. Lohse, Univ. Twente (Netherlands)

TIME-RESOLVED DIAGNOSTIC TECHNIQUES

- 8967 IO **Synchronized videography of plasma plume expansion during femtosecond laser ablation** [8967-36]
S. Paolasini, A. Kietzig, McGill Univ. (Canada)
- 8967 II **Ultrafast imaging of free carriers: controlled excitation with chirped ultrafast laser Bessel beams (Best Student Oral Paper Award)** [8967-37]
P. K. Velpula, M. K. Bhuyan, C. Mauclair, J. P. Colombier, R. Stoian, Lab. Hubert Curien, CNRS, Univ. de Lyon, Univ. Jean Monnet (France)

PROCESSING AND DIAGNOSTICS OF PHOTOVOLTAICS

- 8967 13 **Rapid composition analysis of compound semiconductor thin film solar cell by laser induced breakdown spectroscopy** [8967-39]
S. H. Lee, C. K. Kim, J. H. In, S. H. Jeong, Gwangju Institute of Science and Technology (Korea, Republic of)
- 8967 14 **Modeling of laser patterning of thin-film solar cells** [8967-40]
T. Peschel, Fraunhofer-Institut für Angewandte Optik und Feinmechanik (Germany); G. Matthäus, S. Nolte, Friedrich-Schiller-Univ. Jena (Germany); R. Eberhardt, A. Tünnermann, Fraunhofer-Institut für Angewandte Optik und Feinmechanik (Germany)
- 8967 15 **Optimizing process time of laser drilling processes in solar cell manufacturing by coaxial camera control** [8967-41]
V. Jetter, Fraunhofer-Institut für Physikalische Messtechnik (Germany); S. Gutscher, Fraunhofer-Institut für Solare Energiesysteme (Germany); A. Blug, Fraunhofer-Institut für Physikalische Messtechnik (Germany); A. Knorz, C. Ahrbeck, J. Nekarda, Fraunhofer-Institut für Solare Energiesysteme (Germany); D. Carl, Fraunhofer-Institut für Physikalische Messtechnik (Germany)
- 8967 16 **Silver-free solar cell interconnection by laser spot welding of thin aluminum layers: analysis of process limits for ns- and μ s-lasers** [8967-48]
H. Schulte-Huxel, S. Blankemeyer, S. Kajari-Schröder, Institut für Solarenergieforschung Hameln (Germany); R. Brendel, Institut für Solarenergieforschung Hameln (Germany) and Leibniz Univ. of Hanover (Germany)

PHOTOVOLTAICS AND ENERGY DEVICES: JOINT SESSION WITH CONFERENCES 8967 AND 8968

- 8967 17 **Optimized laser patterning for high performance Cu(In,Ga)Se₂ thin-film solar modules** [8967-43]
A. Burn, M. Murali, Bern Univ. of Applied Sciences (Switzerland); R. Witte, Solneva SA (Switzerland); S. Buecheler, S. Nishiwaki, EMPA (Switzerland); L. Krainer, G. J. Spuehler, Onefive GmbH (Switzerland); V. Romano, Bern Univ. of Applied Sciences (Switzerland)

POSTER SESSION

- 8967 1A **Laser radiation attenuator on the basis of four Dove's prisms** [8967-47]
J. Owsik, Military Univ. of Technology (Poland); A. A. Liberman, A. A. Kovalev, A. S. Mikryukov, S. A. Moskalyuk, M. V. Ulanovsky, All-Russian Research Institute of Optical and Physical Measurements (Russian Federation); J. Noga, Military Univ. of Technology (Poland); A. Rembielińska, LOT Polish Airlines (Poland); J. Walczuk, Agency for Restructuring and Modernisation of Agriculture (Poland)
- 8967 1B **High precision laser forming for microactuation** [8967-49]
G. K. G. P. Folkersma, G. R. B. E. Römer, D. M. Brouwer, A. J. Huis in 't Veld, Univ. Twente (Netherlands)

- 8967 1C **Laser textured substrates for light in-coupling in thin-film solar cells (Best Student Poster Paper Award)** [8967-50]
K. Chakanga, O. Siepmann, O. Sergeev, S. Geißendörfer, K. von Maydell, C. Agert, Next Energy, EWE Research Ctr. for Energy Technology (Germany)
- 8967 1D **Smart optical writing head design for laser-based manufacturing** [8967-51]
M. J. Amin, N. A. Riza, Univ. College Cork (Ireland)
- 8967 1E **High quality ZnO film formation by CO₂ laser annealing of buried films in SiO₂ matrix** [8967-52]
K. Yamasaki, H. Ikenoue, T. Shimogaki, Y. Watanabe, D. Nakamura, T. Okada, Kyushu Univ. (Japan)
- 8967 1F **Selective realignment of the exchange biased magnetization direction in spintronic layer stacks using continuous and pulsed laser radiation** [8967-53]
I. Berthold, M. Müller, R. Ebert, J. Schille, U. Löschner, H. Exner, Hochschule Mittweida (Germany); P. Matthes, M. Albrecht, Technische Univ. Chemnitz (Germany)
- 8967 1G **Shape-controlled ZnO nanocrystals using multi-beam interference irradiation** [8967-54]
D. Nakamura, T. Shimogaki, Y. Muraoka, S. Nakao, K. Harada, M. Higashihata, Kyushu Univ. (Japan); Y. Nakata, Osaka Univ. (Japan); T. Okada, Kyushu Univ. (Japan)
- 8967 1H **Performance optimization of electronic circuits laser repair** [8967-55]
R. Oron, Orbotech Ltd. (Israel)
- 8967 1J **Study of fast laser induced cutting of silicon materials** [8967-57]
S. Weinhold, A. Gruner, R. Ebert, J. Schille, H. Exner, Hochschule Mittweida (Germany)

Author Index

Conference Committee

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Koji Sugioka, RIKEN (Japan)

Session Chairs

- 1 Laser-induced Modification and Patterning of Surfaces I: Joint Session with Conferences 8967 and 8969
Yoshiki Nakata, Osaka University (Japan)
- 2 Laser-induced Modification and Patterning of Surfaces II: Joint Session with Conferences 8967 and 8969
Xianfan Xu, Purdue University (United States)
- 3 Nanomaterial Photonics and Plasmonics I: Joint Session with Conferences 8967 and 8969
Richard F. Haglund Jr., Vanderbilt University (United States)
- 4 Nanomaterial Photonics and Plasmonics II: Joint Session with Conferences 8967 and 8969
Jan J. Dubowski, Université de Sherbrooke (Canada)
- 5 Ultrafast Laser-induced Modifications of Transparent Materials: Joint Session with Conferences 8967 and 8972
Stefan Nolte, Friedrich-Schiller-Universität Jena (Germany)
- 6 Beam Shaping: Joint Session with Conferences 8967 and 8972
Peter R. Herman, University of Toronto (Canada)
- 7 Adaptive Optics and Beam Shaping: Joint Session with Conferences 8967 and 8972
Stephan Roth, BLZ Bayerisches Laserzentrum GmbH (Germany)
- 8 Ultrashort Pulse Micromachining: Joint Session with Conferences 8967 and 8972
Andreas Ostendorf, Ruhr-Universität Bochum (Germany)
- 9 Materials for Energy Conservation
Yongfeng Lu, University of Nebraska-Lincoln (United States)
- 10 Enhanced Processing by Multi-pulse
Stephan Roth, BLZ Bayerisches Laserzentrum GmbH (Germany)
- 11 Annealing and Forming of Microstructures
Klaus Sokolowski-Tinten, Universität Duisburg-Essen (Germany)

- 12 Applications and Diagnostics of Laser Transfer Techniques: Joint Session with Conferences 8967 and 8970
Masayuki Okoshi, National Defense Academy (Japan)
Daisuke Nakamura, Kyushu University (Japan)
- 13 Time-resolved Diagnostic Techniques
Masaaki Sakakura, Kyoto University (Japan)
- 14 Processing and Diagnostics of Photovoltaics
Beat Neuenschwander, Berner Fachhochschule Technik und Informatik (Switzerland)
- 15 Photovoltaics and Energy Devices: Joint Session with Conferences 8967 and 8968
Yoshiki Nakata, Osaka University (Japan)
Udo Klotzbach, Fraunhofer IWS Dresden (Germany)